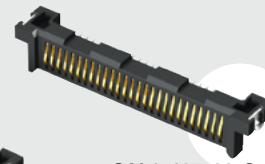


SAL1-140-01-S-S-A-TR



SAL1-127-01-S-S-A-TR

(1.00 mm) .0394"

SAL1 SERIES

HIGH-SPEED THROUGH BOARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SAL1

Insulator Material:

Black LCP

Contact Material:

BeCu

Plating:

Au or Sn over

50 μ " (1.27 μ m) Ni

Operating Temp:

-55 °C to +125 °C

Current Rating:

2.9 A per pin

(2 adjacent pins powered)

RoHS Compliant: Yes

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max

Mates with:

(1.60 mm) .062" or

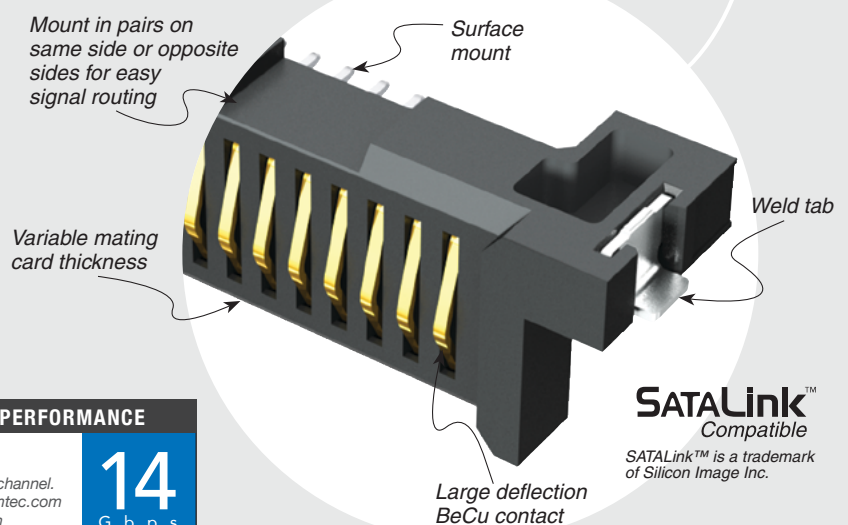
(2.36 mm) .093" card

Mount in pairs on same side or opposite sides for easy signal routing

Surface mount

Variable mating card thickness

Weld tab



SATALink™
Compatible

SATALink™ is a trademark of Silicon Image Inc.

Large deflection BeCu contact

HIGH-SPEED CHANNEL PERFORMANCE

SAL1 (Top Entry)

Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com
or contact SIG@samtec.com

14
Gbps

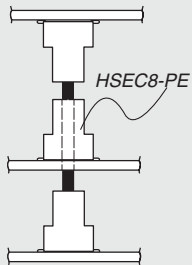
RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

OTHER SOLUTIONS



- Card pass-through option. See HSEC8-PE Series.

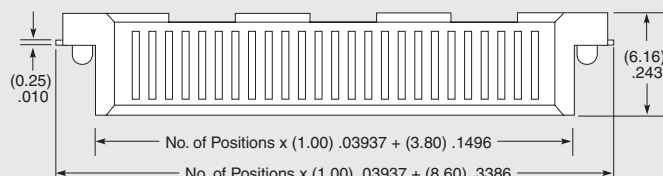
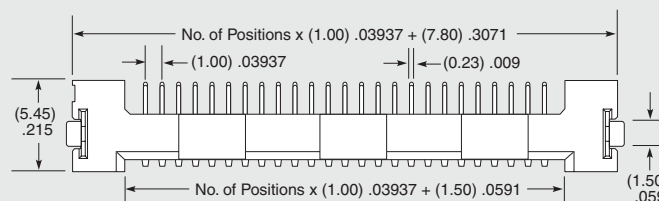
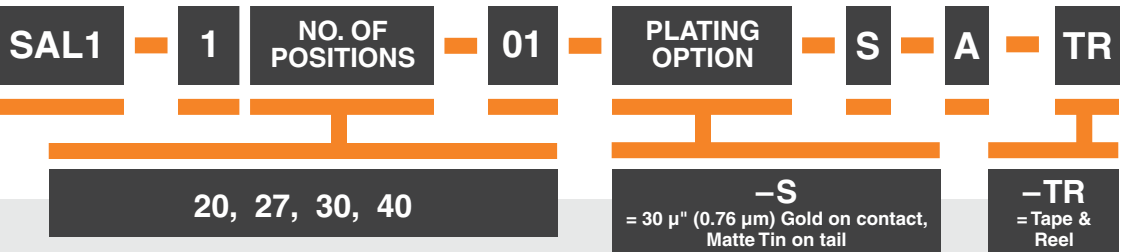
ALSO AVAILABLE (MOQ Required)

- Heavy Gold plating

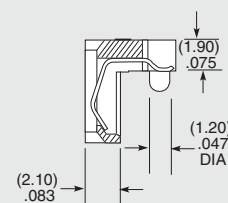
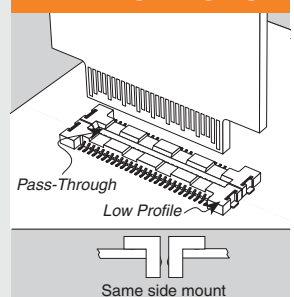
Notes:

While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications.

Some lengths, styles and options are non-standard, non-returnable.



APPLICATIONS



Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.